



NSAI
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Irish Standard
I.S. EN 16602-70-28:2014

Space product assurance - Repair and modification of printed circuit board assemblies for space use

I.S. EN 16602-70-28:2014

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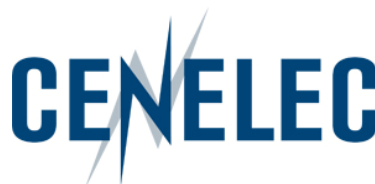
Raumfahrtproduktsicherung - Reparatur und Modifikation
von Leiterplatten-Baugruppen für den Einsatz im Weltraum

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Foreword

This document (EN 16602-70-28:2014) has been prepared by Technical Committee CEN/CLC/TC 5 "Space", the secretariat of which is held by DIN.

This standard (EN 16602-70-28:2014) originates from ECSS-Q-ST-70-28C.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by April 2015, and conflicting national standards shall be withdrawn at the latest by April 2015.

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This document has been prepared under a mandate given to CEN by the European Commission and the European Free Trade Association.

This document has been developed to cover specifically space systems and has therefore precedence over any EN covering the same scope but with a wider domain of applicability (e.g. : aerospace).

According to the CEN-CENELEC Internal Regulations, the national standards organizations of the following countries are bound to implement this European Standard: Austria, Belgium, Bulgaria, Croatia, Cyprus, Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.

1 Scope

The requirements and procedures for repair and modification detailed in this Standard are designed to maintain the rigorous standards set by the customer for the manufacture and assembly of space-quality printed circuit boards.

This Standard is confined to the repair and modification of single-sided, double-sided and multi-layer printed circuit board assemblies.

This Standard does not address the potential need for rework resulting from a repair or modification and unassembled (bare) printed circuits boards.

This standard may be tailored for the specific characteristics and constraints of a space project, in conformance with ECSS-S-ST-00.

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